

Description

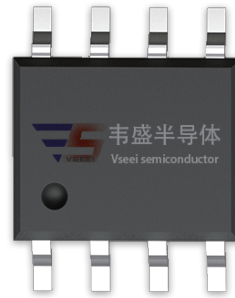
The VSM25P03 uses advanced trench technology to provide excellent $R_{DS(ON)}$. This device is suitable for use as a load switch or power management.

General Features

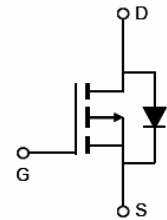
- $V_{DS} = -30V, I_D = -25A$
 $R_{DS(ON)} < 9m\Omega @ V_{GS} = -10V$
 $R_{DS(ON)} < 14m\Omega @ V_{GS} = -4.5V$
- High power and current handling capability
- Lead free product is acquired
- Surface mount package

Application

- Power management
- Load switch



SOP-8



Schematic Diagram

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|----------|----------------|-----------|------------|------------|
| VSM25P03-S8 | VSM25P03 | SOP-8 | Ø330mm | 12mm | 4000 units |

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|----------------|------------|------------------|
| Drain-Source Voltage | V_{DS} | -30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | -25 | A |
| Drain Current-Pulsed ^(Note 1) | I_{DM} | -70 | A |
| Maximum Power Dissipation | P_D | 3.5 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | $^\circ\text{C}$ |

Thermal Characteristic

| | | | |
|---|-----------------|----|--------------------|
| Thermal Resistance, Junction-to-Ambient ^(Note 2) | $R_{\theta JA}$ | 36 | $^\circ\text{C/W}$ |
|---|-----------------|----|--------------------|

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

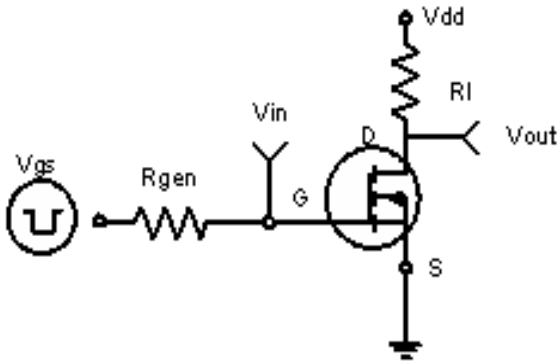
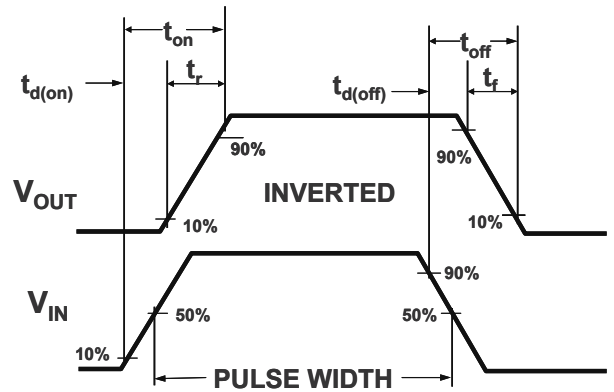
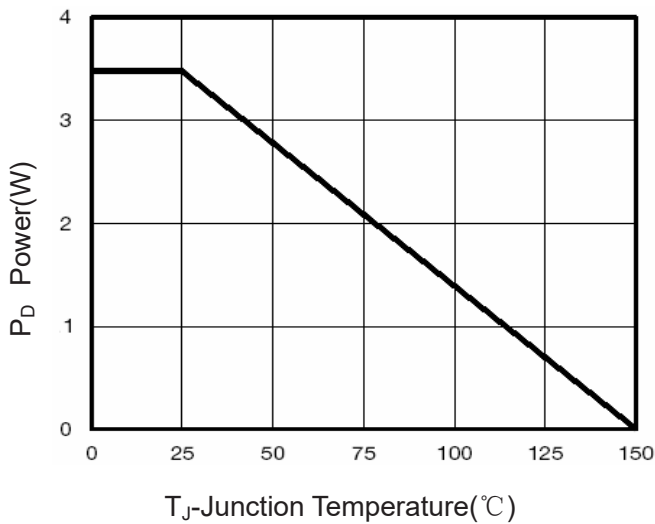
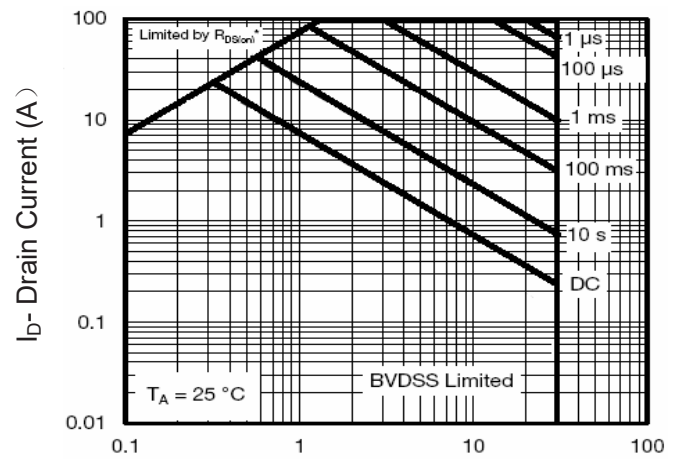
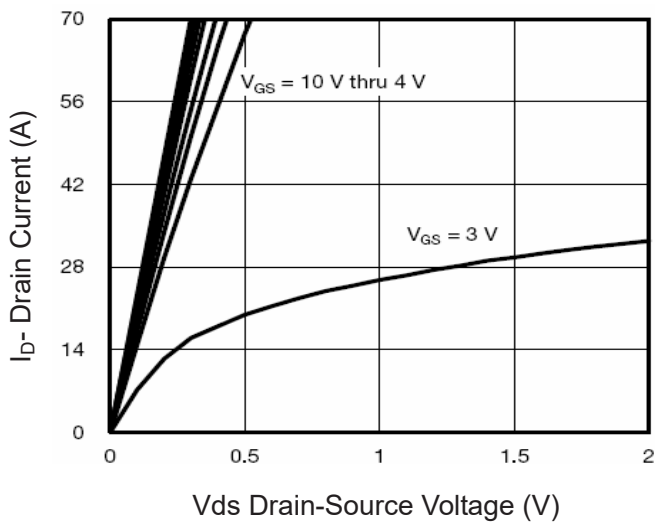
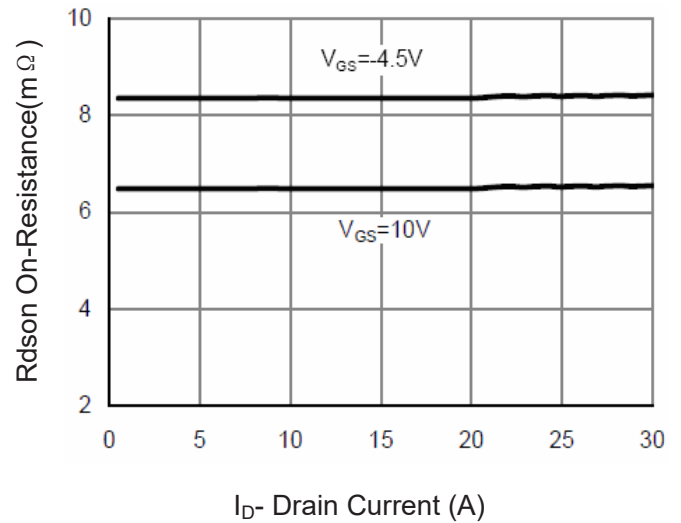
| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--------------------------------|------------|----------------------------|-----|-----|-----|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=-250\mu A$ | -30 | -33 | - | V |

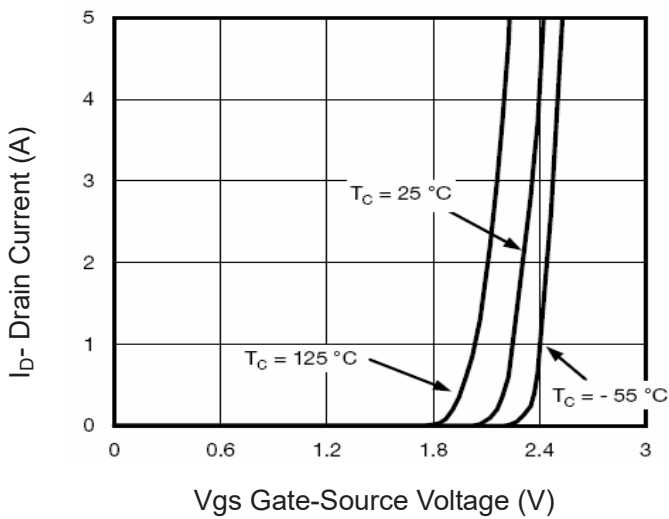
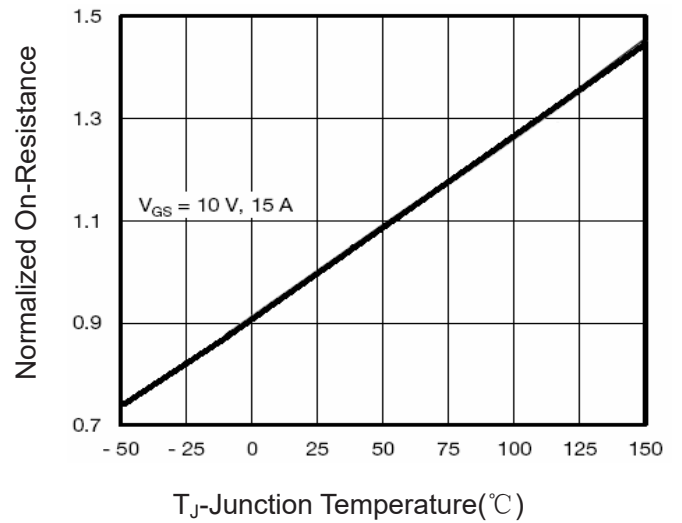
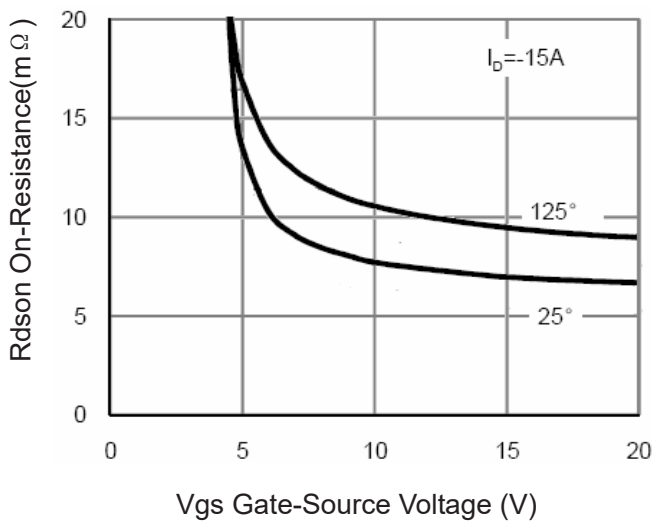
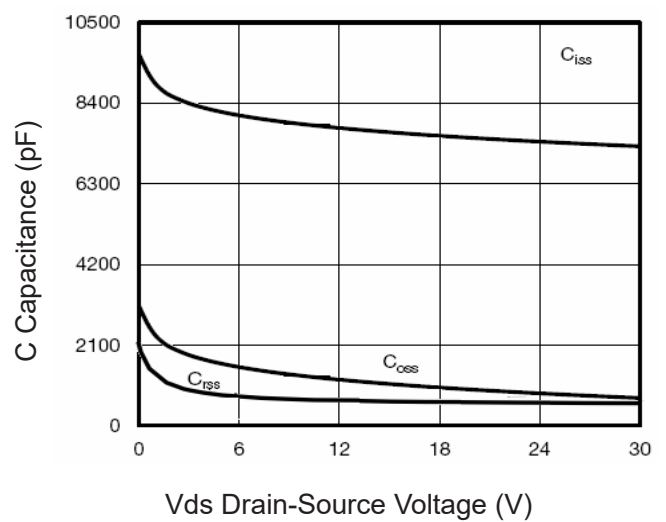
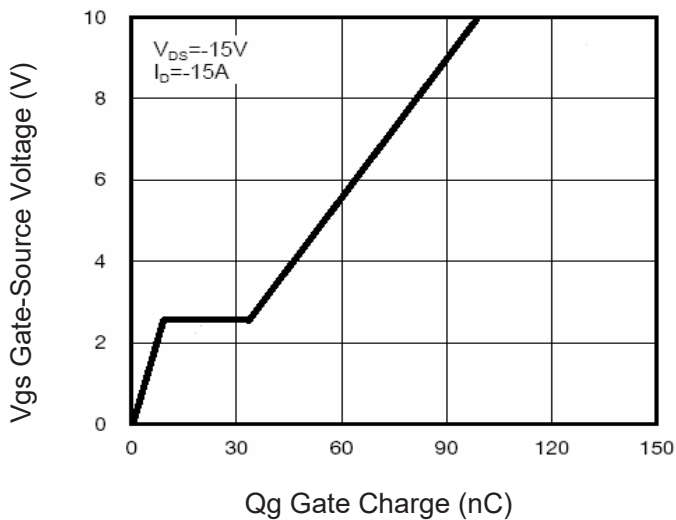
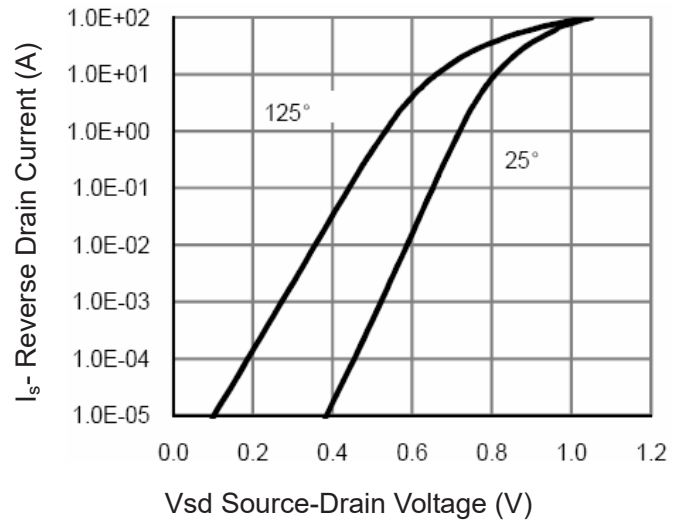


| | | | | | | |
|---|--------------|--|------|------|-----------|------------|
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=-30V, V_{GS}=0V$ | - | - | -1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -1.0 | -1.5 | -2.5 | V |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}=-10V, I_D=-15A$ | - | 6.4 | 9 | m Ω |
| | $R_{DS(ON)}$ | $V_{GS}=-4.5V, I_D=-15A$ | - | 8.3 | 14 | |
| Forward Transconductance | g_{FS} | $V_{DS}=-10V, I_D=-15A$ | 30 | - | - | S |
| Dynamic Characteristics (Note4) | | | | | | |
| Input Capacitance | C_{ISS} | $V_{DS}=-15V, V_{GS}=0V,$ $F=1.0MHz$ | 6500 | 7506 | 8500 | PF |
| Output Capacitance | C_{OSS} | | - | 901 | - | PF |
| Reverse Transfer Capacitance | C_{RSS} | | - | 742 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=-15V, I_D=-15A,$ $V_{GS}=-10V, R_{GEN}=3\Omega$ | - | 50 | - | nS |
| Turn-on Rise Time | t_r | | - | 60 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 60 | - | nS |
| Turn-Off Fall Time | t_f | | - | 21 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=-15V, I_D=-15A, V_{GS}=-10V$ | - | 98.9 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 11.4 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 20.3 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V_{SD} | $V_{GS}=0V, I_S=-25A$ | - | - | -1.2 | V |

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

Figure 1 Switching Test Circuit

Figure 2 Switching Waveforms

Figure 3 Power Dissipation

Figure 4 Safe Operation Area

Figure 5 Output Characteristics

Figure 6 Drain-Source On-Resistance


Figure 7 Transfer Characteristics

Figure 8 Drain-Source On-Resistance

Figure 9 Rdson vs Vgs

Figure 10 Capacitance vs Vds

Figure 11 Gate Charge

Figure 12 Source- Drain Diode Forward

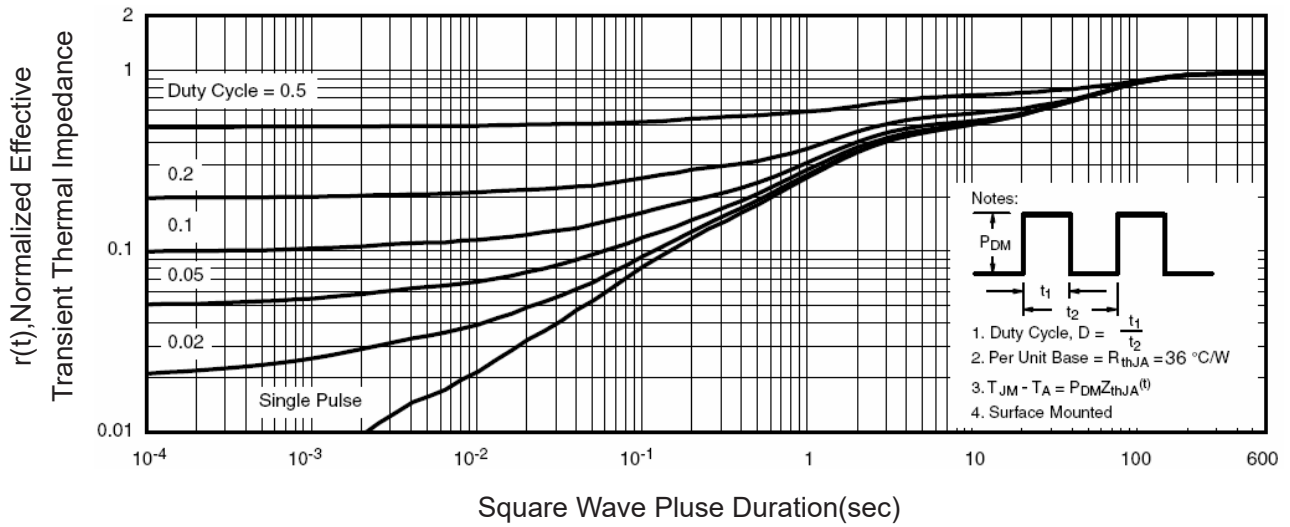


Figure 13 Normalized Maximum Transient Thermal Impedance